Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

Created on: 06/08/2022

Details for "THVD1500DR"

Current Product Information

١	Ti part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
	THVD1500DR	NIPDAU	Level-1-260C-UNLIM	TI AGUASCALIENTES	D 8	4.9x3.9x1.75	107.5

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.085166	99.998826	999988	0.07924	792
Precious Metals	Silver	7440-22-4	0.000001	0.001174	12	0.000001	-
Sub-Total			0.085167	100	1000000	0.079241	792
Die Attach Adhesive	ie Attach Adhesive						
Precious Metals	Silver	7440-22-4	0.100406	79.000126	790001	0.093419	934
Thermoplastics	Ероху	85954-11-6	0.02669	20.999874	209999	0.024833	248
Sub-Total			0.127096	100	1000000	0.118252	1183
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	40.49388	96.414	964140	37.67616	376762
Copper and Its Alloys	Iron	7439-89-6	1.092	2.6	26000	1.016014	10160
Copper and Its Alloys	Phosphorus	7723-14-0	0.063	0.15	1500	0.058616	586
Nickel and Its Alloys	Nickel	7440-02-0	0.336	0.8	8000	0.31262	3126
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0042	0.01	100	0.003908	39
Precious Metals	Gold	7440-57-5	0.0042	0.01	100	0.003908	39
Precious Metals	Palladium	7440-05-3	0.00672	0.016	160	0.006252	63
Sub-Total			42	100	1000000	39.077479	390775
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	3.99504	95.12	951200	3.71705	37170
Precious Metals	Gold	7440-57-5	0.03276	0.78	7800	0.03048	305
Precious Metals	Palladium	7440-05-3	0.1722	4.1	41000	0.160218	1602
Sub-Total			4.2	100	1000000	3.907748	3907
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	53.331815	88	880000	49.620782	496208
Other Plastics and Rubber	Carbon Black	1333-86-4	0.181813	0.3	3000	0.169162	1692
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.333324	0.55	5500	0.31013	310
Thermoplastics	Ероху	85954-11-6	6.757383	11.149999	111500	6.287178	6287
Sub-Total			60.604335	100	1000000	56.387252	56387
Semiconductor Device		•					
Ceramics / Glass	Doped Silicon	7440-21-3	0.462189	100	1000000	0.430028	4300
Sub-Total			0.462189	100	1000000	0.430028	430
Total			107.478787			100	100000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page

Product Content Methodology
For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-Free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is. For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/08/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures. TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the ROHS Annex II threshold, but that fall within one of the specific ROHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.